

IN THE SPECIFICATION:

Page 3, lines 4-12, rewrite paragraph as follows:

The body further has an exposed surface (11) that is not covered by the outer terminals (14). The zinc oxide semiconductor filler (~~13~~12) is fabricated using the HTCC process with additives, such as manganese oxide, nickel oxide, cobalt oxide, etc. metal oxide materials. The raw metal oxide materials can be fabricated from an organic salt or inorganic salt, such as carbonate or oxalate. The outer terminals (14) can be made of silver or a metal compound consisting of silver, platinum or palladium ~~with frit~~. The outer terminals (14) can be fabricated with a printing method, a rolling method, a spraying method, etc. Further, the form of the body (10) can be a rectangle, cylinder, hollow cylinder, etc.